

Supplementary Materials: Crack-Resistance Behavior of an Encapsulated, Healing Agent Embedded Buffer Layer on Self - Healing Thermal Barrier Coatings

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Table S1. Particle diameters at 10%, 50%, and 90% of the cumulative mass of (A): normal Si, and (B) encapsulated Si from Figure 5.

D-values (μm)	d (0.1)	d (0.5)	d (0.9)
A	2.461	8.600	23.851
B	2.281	8.543	24.760

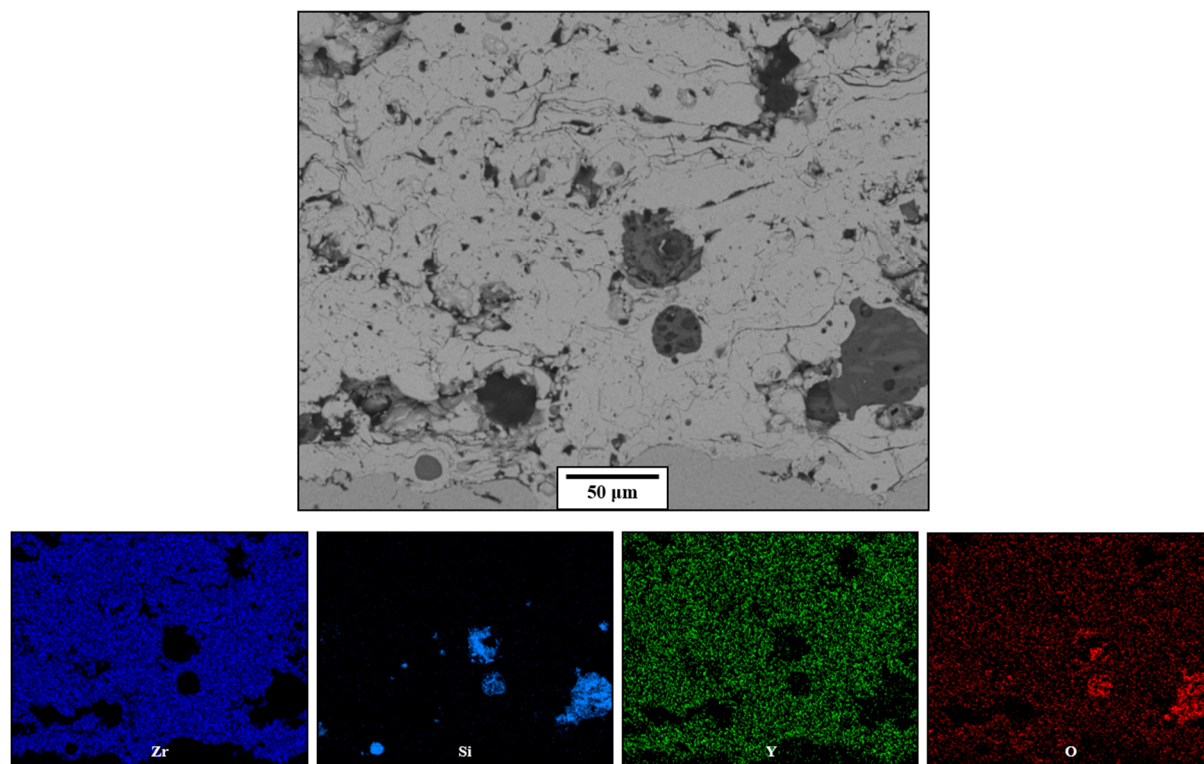


Figure S1. EDS mapping analysis around the healing agents in as-coated samples from Figure 6(C-1).

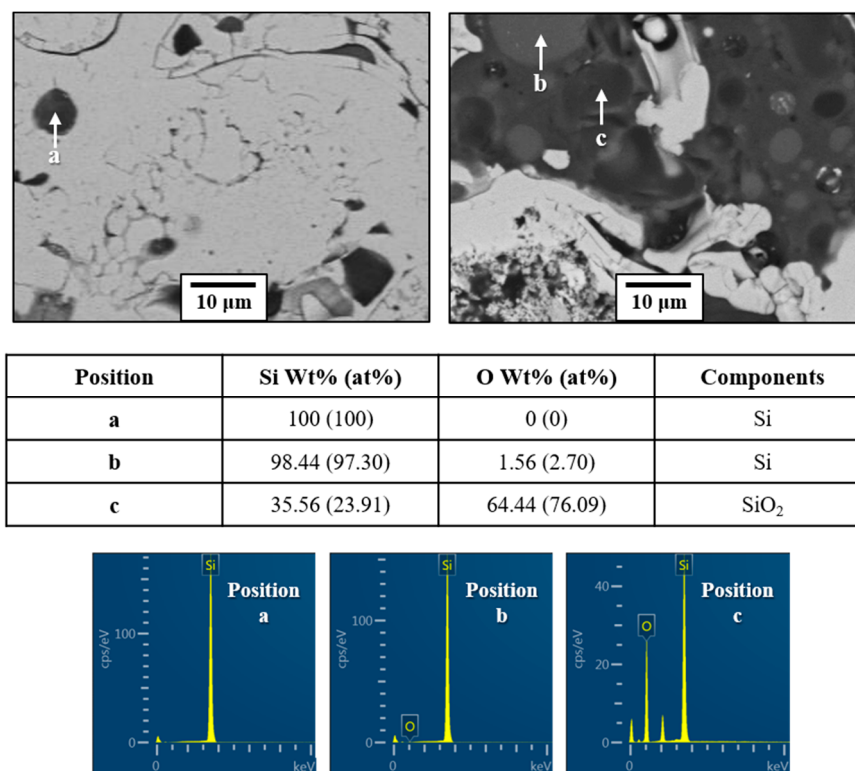


Figure S2. EDS point-analysis around the healing agents in as-coated samples from Figure 7A,B.

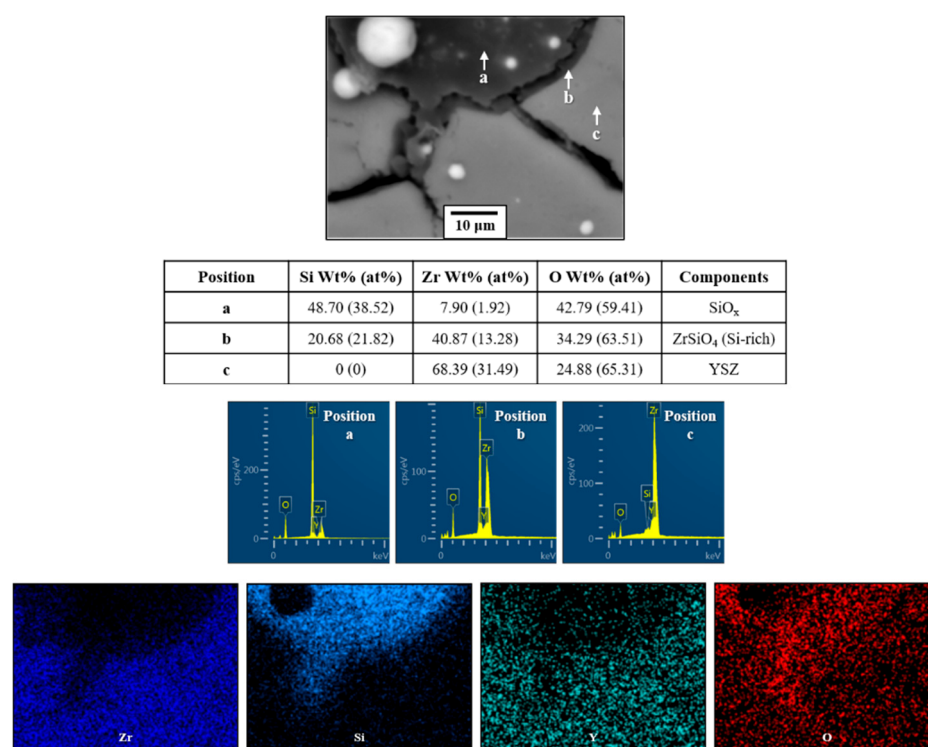


Figure S3. EDS point- and mapping analysis around the healing agents after heat treatment from the magnified image in Figure 10C.

